

FEATURES

Surface Mounting Design 5.5*5.5*6.0mm

High Current Handling Capability 10,000A @ 8/20 μs

Low Capacitance and Insertion Loss

| Quick Response and Long Service Life

| Moisture sensitivity level: Level 1



5.5*5.5*6.0mm



Schematic Symbol

APPLICATION INFORMATION

Communication equipment.

Repeaters, Modems

| Telephone Interface,Line cards.

Data communication equipment.

AGENCY APPROVALS

lcon	Solderability	
RoHS	Compliance with 2011/65/EU	
HF	Compliance with IEC61249-2-21:2003	
%	Mean lead free	

PRODUCT CHARACTERISTICS

Lead Material	Body Material	Terminal Finish
Copper or Fe-Ni alloy	Ceramics	100% Matte-Tin Plated



ELECTRICAL PARAMETER

Parameter	Symbol	Limit	Unit
DC Blocking Voltage 1)	100V/s	72-108	V
Impulse Spark-over Voltage	At 1kV/μs	for 99 % of measured values ≤ 900	V
	At 1kV/μs	Typical values of distribution ≤850	V
Impulse Discharge Current 2)	8/20µs	10,000	А
Insulation Resistance	DC=50V	≥ 1	GΩ
Capacitance at 1MHz	V _{DC} =0.5V	≤ 1.5	рF
Operating And Storage Temperature		-40-125	°C

¹⁾ In ionized mode

ENVIRONMENTAL RELIABILITY CHARACTERISTICS

Testing items Technical standards		
High Temperature Storage Test	Temperature: 85°C ;Time:2H	
Low Temperature Storage Test	Temperature: -40°C ; Time:2H	
Vibration	Frequency: 10-500Hz ; Amplitude: 0.15mm ; Time:45min	
Resistance of soldering heat	Temperature: 260±5°C; Time of dip soldering: 10s, 1time	

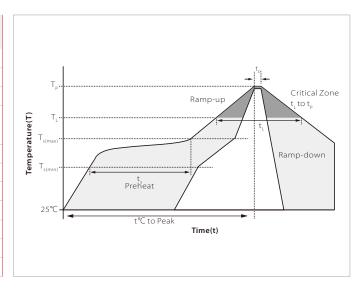
NOTE: Up-screen program can be specified by customer's request via contacting Semiware service

²⁾ Terms and waveforms in accordance with ITU-T Rec. K. 12; IEC 61643-21

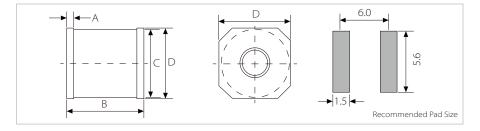


REFLOW PROFILE

Reflow Condition		Lead-free assembly	
	Temperature Min	150°C	
Pre Heat	Temperature Max	200°C	
	Time(min to max)	60 – 180 secs	
Average ra	amp up rate (Liquidus)Temp (T_L) to peak	3°C/second max	
	T_s (max)to T_L - Ramp-up Rate		
Reflow	Temperature (T _L) (Liquidus)	217℃	
Ketiow	Time(min to max)(t_s)	60 – 150 seconds	
PeakTem	perature (T,)	260 °C	
Time within 5°C of actual peak Temperature (tp)		10-30 seconds	
Ramp-down Rate		6°C/second max	
Time 25°C to peak Temperature (T₂)		8 minutes max.	
Do not exceed		260°C	



PRODUCT DIMENSIONS AND RECOMMENDED SOLDERING PAD



Ref.	Outline Dimensions	
Kei.	Millimeters	
А	0.5±0.2	
В	6.0±0.2	
С	5.4±0.2	
D	5.5±0.2	

ORDERING INFORMATION

Part Number	Size	Marking	QTY/Reel	Reel Size
SG2R05B090C	5.5*5.5*6.0mm	愛 SG090 <u>05</u>	1000PCS	13″



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By QR Code





Website

Machat

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